

AMENDMENTS TO THE SPECIFICATION

At page 1, lines 3-4, please amend the Title as follows:

**COPPERBRONZE-BASED ALLOY AND INGOT AND LIQUID-CONTACTING
PART USING THE ALLOY**

**Please amend paragraph [0007], page 3, lines 22-30 to page 4, line 1 of the
specification as follows:**

[0007] To attain the above object, an embodiment of the present invention of
~~claim 1~~ is directed to a copper-based alloy having soundness of alloy improved during a course
of solidification of the copper-based alloy by crystallizing an intermetallic compound capable of
solidifying at a temperature exceeding a solidus line in dendritic gaps of the alloy, suppressing
migration of a solute, thereby allowing dispersion of microporosities, utilizing crystallization of
the intermetallic compound as well for effecting dispersed crystallization of a low melting metal
or a low melting intermetallic compound capable of solidifying at a temperature falling short of a
liquidus line, and relying on the low melting metal or low melting intermetallic compound to
enter the microporosities and suppress occurrence of microporosities.

Please amend page 4, paragraph [0008], lines 2-5 of the specification as follows:

[0008] The invention of claim 2 An embodiment of the present invention is directed
to the copper-based alloy containing at least 5.0 to 10.0 weight% of Zn and $0 < \text{Se} \leq 1.5$ weight% of
Se and having ZnSe crystallized as the intermetallic compound in the dendritic gaps of the alloy
during the course of solidification of the copper-based alloy.

Please amend page 4, paragraph [0009], lines 6-7 of the specification as follows:

[0009] The invention of claim 3 An embodiment of the present invention is directed
to the copper-based alloy, wherein the intermetallic compound has a surface ratio of 0.3% or more
and 5.0% or less.

Please amend page 4, paragraph [0010], lines 8-10 of the specification as follows:

[0010] ~~The invention of claim 4~~ An embodiment of the present invention is directed to the copper-based alloy containing at least 0.25 to 3.0 weight% of Bi and having Bi crystallized as the low melting metal in a region of the solute during the course of solidification of the copper-based alloy.

Please amend page 4, paragraph [0011], lines 11-13 of the specification as follows:

[0011] ~~The invention of claim 5~~ An embodiment of the present invention is directed to the copper-based alloy, wherein the low melting metal or low melting intermetallic compound has a surface ratio of 0.2% or more and 2.5% or less.

Please amend page 4, paragraph [0012], lines 14-17 of the specification as follows:

[0012] ~~The invention of claim 6~~ An embodiment of the present invention is directed to the copper-based alloy that comprises at least 5.0 to 10.0 weight% of Zn, 2.8 to 5.0 weight% of Sn, 0.25 to 3.0 weight% of Bi, $0 < \text{Se} \leq 1.5$ weight% of Se, less than 0.5 weight% of P, the balance of Cu and less than 0.2 weight% of Pb as an unavoidable impurity.

Please amend page 4, paragraph [0013], lines 18-20 of the specification as follows:

[0013] An ingot produced using the copper-based alloy according to ~~any of claims 1 to 6~~ an embodiment of the present invention or a liquid-contacting part having the copper-based alloy mechanically formed.

Please amend page 4, paragraph [0014], lines 22-29 of the specification as follows:

Effect of the Invention:

[0014] In accordance with an embodiment of the present invention recited in claim 4, by dispersing microporosities to prevent the microporosities from occurring concentrically in the central part of an alloy, allowing as well the dispersed low melting metal or low melting intermetallic compound to enter the microporosities, and consequently restraining

effectively the occurrence of the microporosities, it is made possible to provide a copper-based alloy that enhances the soundness of alloy and secures a prescribed property of pressure resistance.

Please amend page 5, paragraph [0015], lines 1-3 of the specification as follows:

[0015] In accordance with an embodiment of the present invention-recited in-claim 2 or 3, it is made possible to provide a copper-based alloy that suppresses a rare metal content, enhances the soundness of alloy and excels in economy as well.

Please amend page 5, paragraph [0016], lines 4-6 of the specification as follows:

[0016] In accordance with an embodiment of the present invention-recited in-claim 4 or claim 5, it is made possible to provide a copper-based alloy that suppresses a rare metal content, enhances the soundness of alloy and excels in economy as well.

Please amend page 5, paragraph [0017], lines 7-12 of the specification as follows:

[0017] In accordance with an embodiment of the present invention-set forth in-claim 6, it is made possible to obtain even in such a bronze that satisfies a prescribed standard lead elution and manifests a wide range of solidifying temperature a copper-based alloy which allows microporosities to be decreased in the central part of wall thickness of the alloy and enhances the soundness of alloy and particularly a copper-based alloy befitting general plumbing materials, such as valves, for example.

Please amend page 5, paragraph [0018], lines 13-20 of the specification as follows:

[0018] In accordance with an embodiment of the present invention-set forth in-claim 7, it is made possible to provide an ingot as an intermediate and provide valve parts including valves, stems, valve seats and disks for potable water, plumbing materials including faucets and joints, devices for service and drain pipes including strainers, pumps and motors which are fated to contact liquids, liquid-contacting faucet fittings, hot water-handling devices

including hot feed water devices, parts and members for clean water lines, and intermediates including coils and hollow bars other than the finished products and assembled bodies enumerated above.